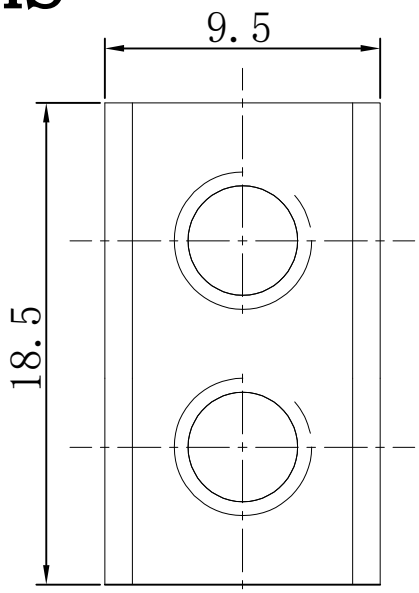
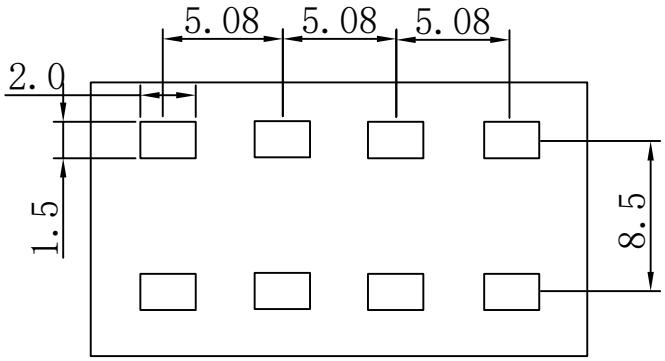
RoHS

REV.	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	新版发行			2026.03.17

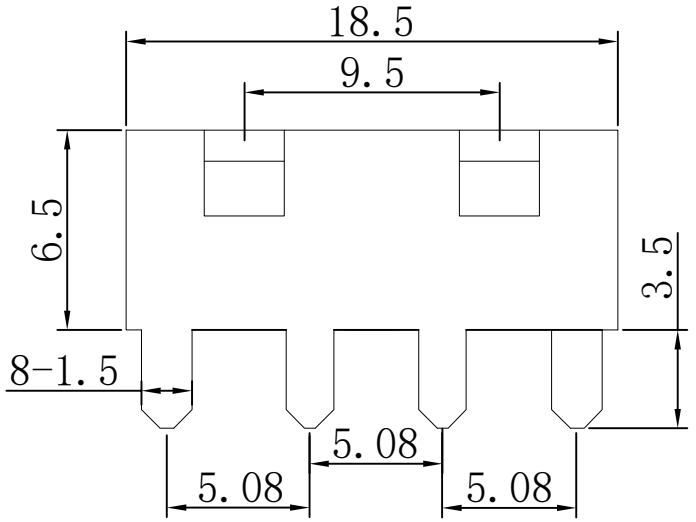


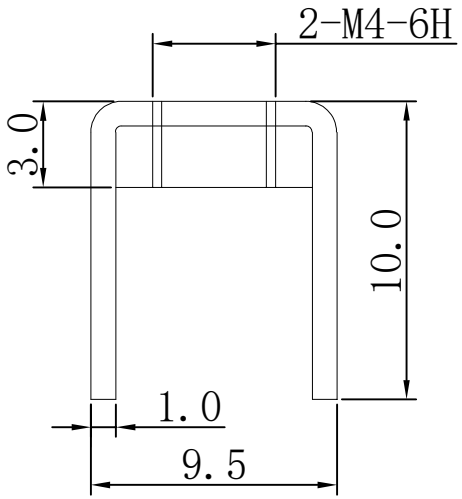


技术要求：

1.打铜底0.5-1μm,镍2-2.5μm，镀雾锡3-5μm。
2.铆好后不得有松动现象。
3.插脚尖部符合可焊性要求。
4.螺纹需符合通止规/止针要求。
5.螺纹扭矩：1.4Nm.
6.额定电流 ： 50A.

PCB LAYOUT





序号	名称	零件编号	材质	数量
2	垫片		SPCC	1
1	插脚		H62(Y2)	1

＞30.±0.4	X.°±
6-30±0.3	.X°±
0-6±0.2	.XX°±
ANGLES±1°	.XXX°±
UNITS:	mm

THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF XFCN AND SHALL NOT BE REPRODUCED,COPIED OR CUED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF XFCN

PART NO: TT48095185-1000

TITLE: PCB SOLDERING TERMINAL

APPD	Chen ZhiQiang			
CHKD	Liu Wei	VIEW		
DRAW	Chen HongJiang	SCALE	SHEET	REV
DATE	2026.03.17	NONE	1/1	A1

XFCN 兴飞连接器
0769-82001899
www.xfconn.com

DWG NO: /